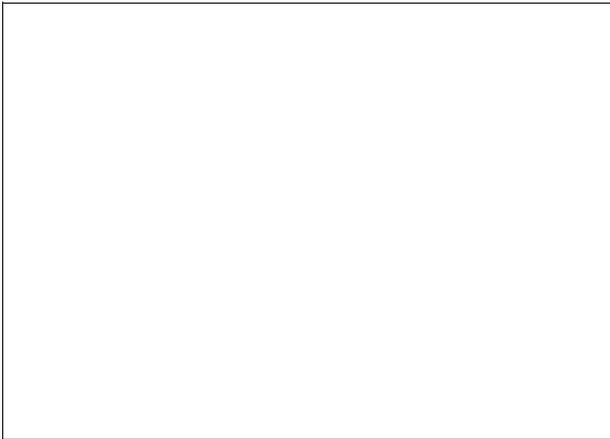

Precise and fast bonding systems with the aid of USB 2.0 camera mvBlueFOX (Vision: 4-B31)

Running like clockwork

"The more chips per wafer - the lower manufacturing costs" - in the semiconductor industry this slogan is very popular and it leads to smaller - however - more fragile chips. The handling of chips in the post processing like the separation, the mounting, the contracting and the encapsulation is a challenge - also for the optical component, which means the industrial camera from MATRIX VISION.

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